



Session Title:	[ThC2] Process and Integration
Session Date:	November 14 (Thu.), 2024
Session Time:	10:50-12:40
Session Room:	Room C (Grand Ballroom 3, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Changhwan Choi (Hanyang Univ., Korea)

[ThC2-1] [Invited]

10:50-11:20

Technology Trends of Memory Packages for High Performance Computing Memory in AI Era
Heejin Lee (SK hynix Inc., Korea)

[ThC2-2] [Invited]

11:20-11:45

Negative Type Bump Photoresist for Advanced Package

Seungkeun Oh, Jung-woo Kim, Myoung-hyun Hur, and Jaehyun Kim (Dongjin Semichem Co., Ltd., Korea)

[ThC2-3] [Invited]

11:45-12:10

AFM Measurement Techniques in Advanced Packaging and Hybrid Bonding Processes

Byoung-woon Ahn, Ah-jin Jo, Sang-han Chung, Seung-yeon Sung, and Dongchun Lee (Park Systems Corp., Korea)

[ThC2-4] [Invited] – Pre-recorded

12:10-12:40

An Innovative 2D/3D Chiplelets Integration with Fan-out Switching Chip

Wei-Chung Lo, Feng-Hsiang Lo, Chin-Hung Wang, Ching-Iang Li, Yung-Sheng Chang, Jie Zhang, Chao-Kai Hsu, Tsung-Yi Hung, and Tsung-Yu Ou Yang (Industrial Tech. Research Inst., Taiwan)